

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.86457	100.0	64.02
				Subtotal	0.86457	100
						64.02
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00165	100.0	0.12231
	Pure metal	Aluminium (Al)	7429-90-5	0.13284	100.0	9.83664
				Subtotal	0.13449	200
						9.95895
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01967	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06558	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	65.49375	99.87	4,849.6872
				Subtotal	65.579	100
						NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.31266	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.92248	15.0	364.5
	Filler	Silica fused	60676-86-0	24.28422	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.29716	7.0	170.1
				Subtotal	32.81652	100
						NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40514	100.0	30
				Subtotal	0.40514	100
						30
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.13018	65.0	9.63934
	Lead alloy	Silver (Ag)	7440-22-4	0.05007	25.0	3.70744
	Lead alloy	Antimony (Sb)	7440-36-0	0.02003	10.0	1.48298
				Subtotal	0.20028	100
						14.82976
				Total	100	100
						NaN

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